Features

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

ullet Package : 500pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant

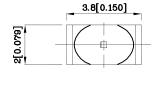


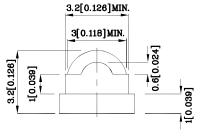




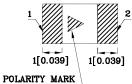
ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Schematics









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- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	DG (InGaN)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V
Forward Current	I_{F}	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA
Power Dissipation	P_{D}	102.5	mW
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)	450	V	

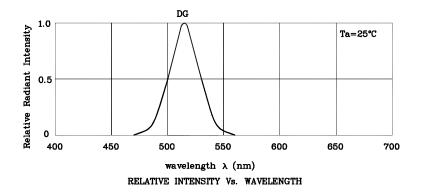
Operating Characteristics (T _A =25°C)		DG (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4.1	V
Reverse Current (Max.) $(V_R=5V)$	I_R	50	uA
Wavelength of Peak Emission (Typ.) $(I_F=20 \text{mA})$	λΡ	515	nm
Wavelength of Dominant Emission (Typ.) $(I_F=20 \text{mA})$	λD	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	рF

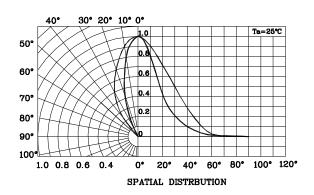
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZDG79W	Green	InGaN	Water Clear	700	1295	515	60°(H) 35°(V)

Apr 13,2011 XDSB3916 V3 Layout: Maggie L.

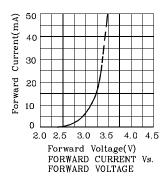


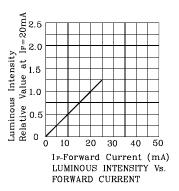


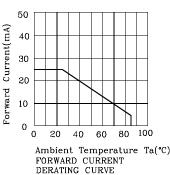


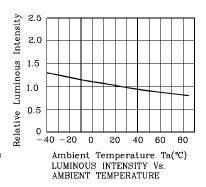


♦ DG



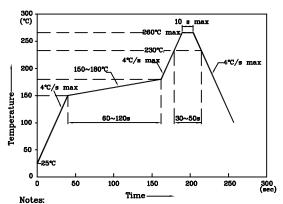






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

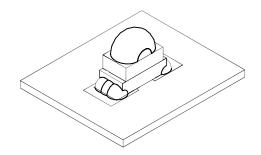
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XDSB3916 V3 Layout: Maggie L.

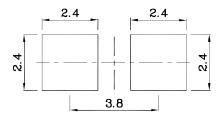




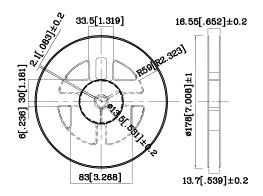
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



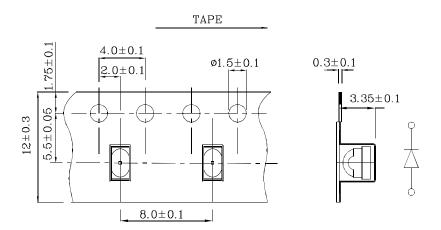
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

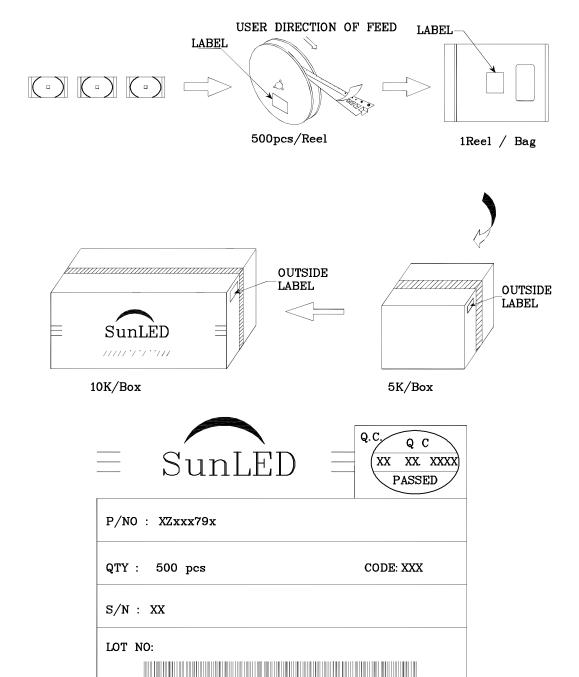
Note: Accuracy may depend on the sorting parameters.

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PACKING & LABEL SPECIFICATIONS



Apr 13,2011

RoHS Compliant